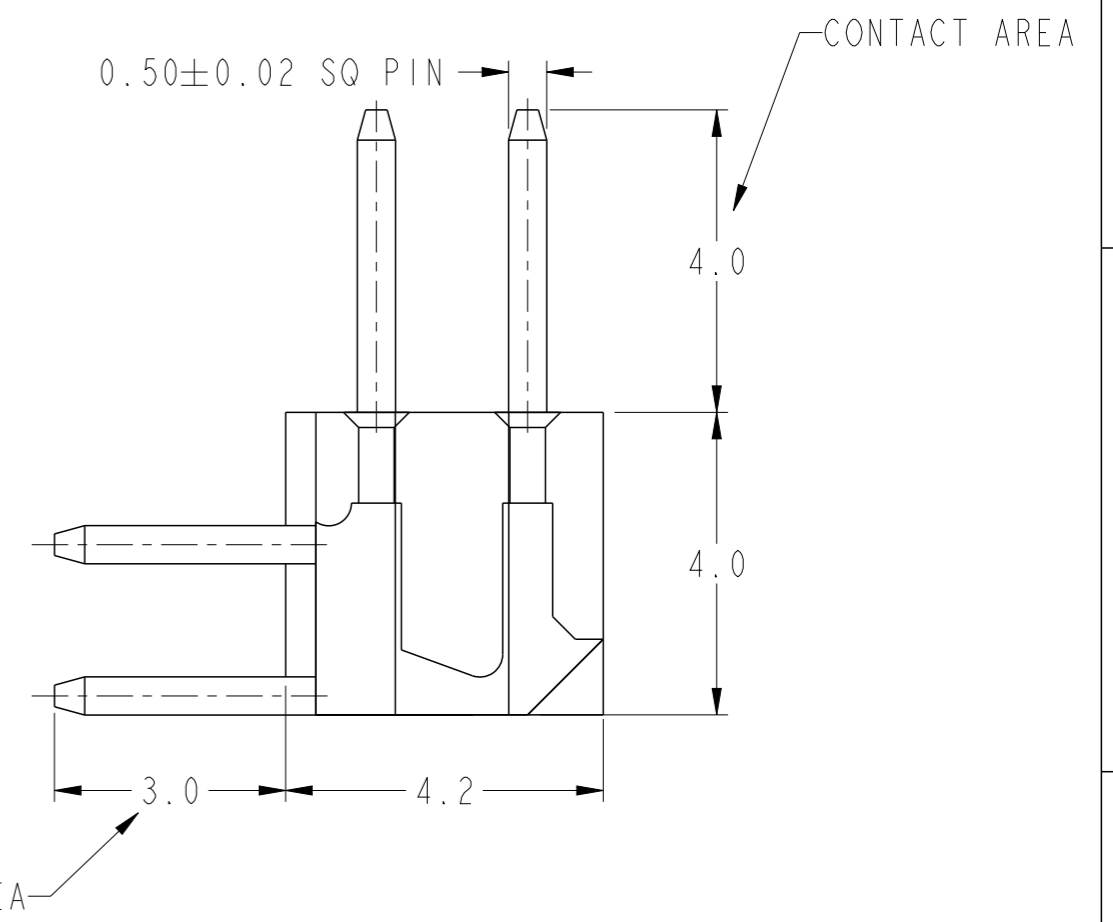
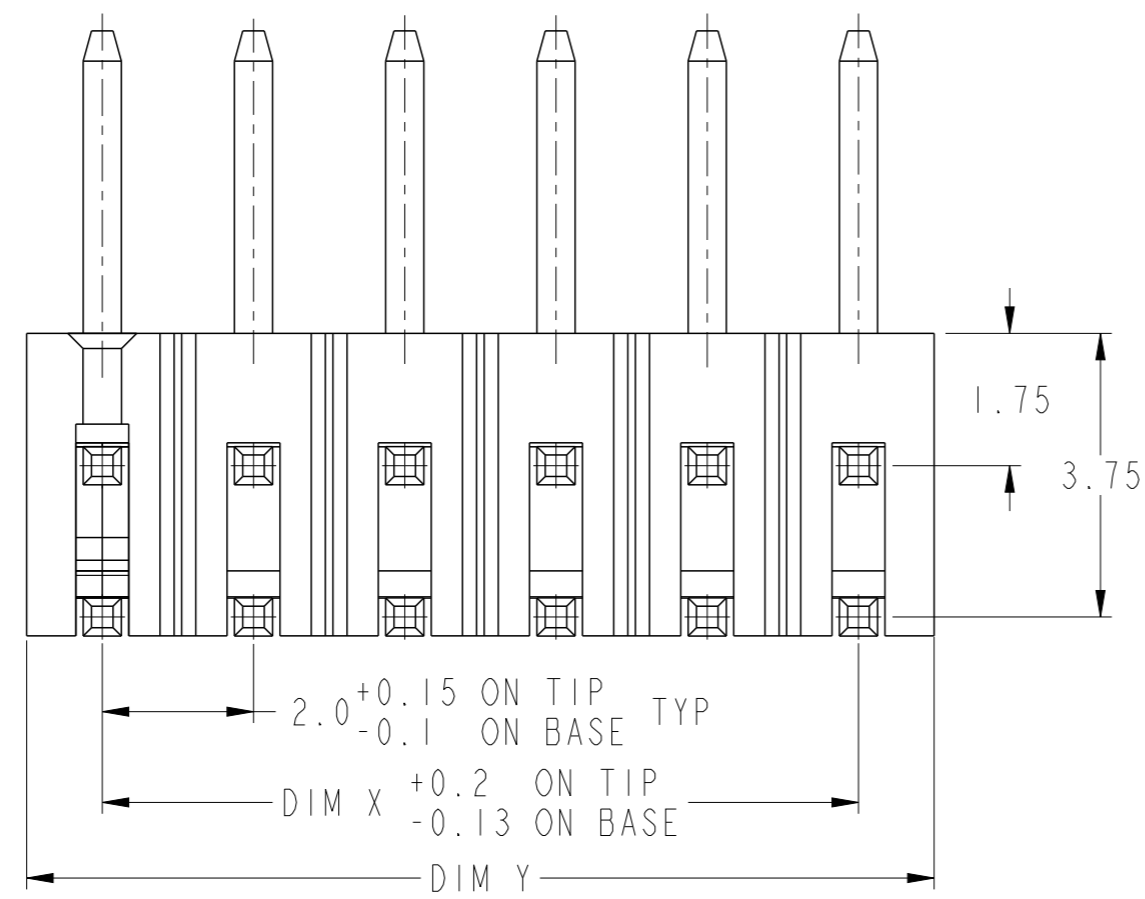


SCALE 5:1

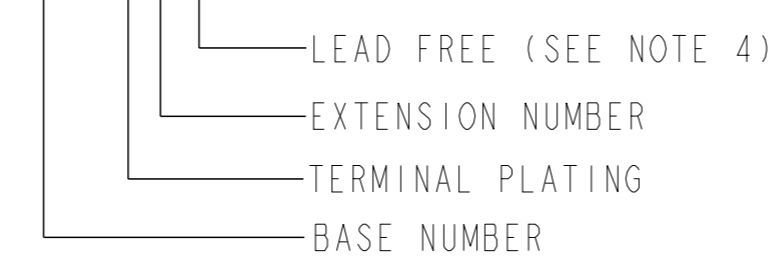


spec ref	-	dr	Andrew Yong	2010/10/22	projection	MM	size	A3	scale	10:1	
tolerance std	ISO 406 ISO 1101	eng	Yuan-Yuan Bao	2021/08/10			ecn no	ELX-N-41765-1			
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	-			rel level	Released			
surface	linear	appr	Tim Yao	2021/08/11	product family	-	dwg no	94277		rev	F
ISO 1302	angular	Amphenol FCI		MINITEK II R/A HEADER			cat. no.		-	Product - Customer Drw	sheet 1 of 2
	0.X	±									
	0.XX	±0.25									
	0.XXX	±									
	0°	±3°									

PRODUCT NO	POS	DIM X	DIM Y
94277-X04	2 X 2	2	4
X06	2 X 3	4	6
X08	2 X 4	6	8
X10	2 X 5	8	10
X12	2 X 6	10	12
X14	2 X 7	12	14
X16	2 X 8	14	16
X18	2 X 9	16	18
X20	2 X 10	18	20
X22	2 X 11	20	22
X24	2 X 12	22	24
X26	2 X 13	24	26
X28	2 X 14	26	28
X30	2 X 15	28	30
X32	2 X 16	30	32
X34	2 X 17	32	34
X36	2 X 18	34	36
X38	2 X 19	36	38
X40	2 X 20	38	40
X42	2 X 21	40	42
X44	2 X 22	42	44
X46	2 X 23	44	46
X48	2 X 24	46	48
X50	2 X 25	48	50

PRODUCT DESCRIPTION CODE :

XXXXX-XXXLF



NOTES:

- MATERIAL:
BODY : HIGH TEMPERATURE PLASTIC UL 94V-0 BLACK
PIN : COPPER ALLOY
- TOLERANCE UNLESS OTHERWISE NOTED ± 0.25
- STAND-OFF DESIGN FOR 2X2 POS. REFERS TO FIG. 1.
- P/N:94277-XXXLF IS SAME AS P/N:94277-XXX. THE SUFFIX 'LF' IS ADDED JUST FOR EASY LEAD FREE IDENTIFICATION
- THE HOUSING WILL WITHSTAND EXPOSURE TO 255°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- PACKAGE:94277-XXXLF STANDARD PACKAGE IN BAG,
94277-XXXTRLF PACKAGE IN TAPE REEL.

PLATING	DESCRIPTION
0	0.20 μ m Au OVER Ni
1	0.76 μ m Au OVER Ni
3	0.38 μ m Au OVER Ni
5	0.38 μ m PdNi W Au FLASH OVER Ni
6	0.76 μ m PdNi W Au FLASH OVER Ni
7	0.76 μ m AU OVER NI ON CONTACT AREA 2.54 μ m MATTE TIN OVER NI ON SOLDER AREA
8	0.38 μ m AU OVER NI ON CONTACT AREA 2.54 μ m MATTE TIN OVER NI ON SOLDER AREA
9	0.20 μ m AU OVER NI ON CONTACT AREA 2.54 μ m MATTE TIN OVER NI ON SOLDER AREA
A	GOLD FLASH OVER NI ON CONTACT AREA 2.54 μ m MATTE TIN OVER NI ON SOLDER AREA
B	2.54 μ m MATTE TIN OVER NI OVERALL

Amphenol FCI

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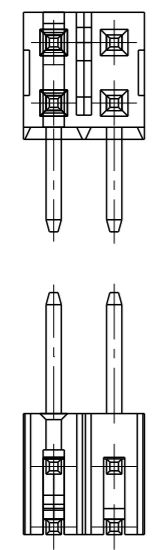
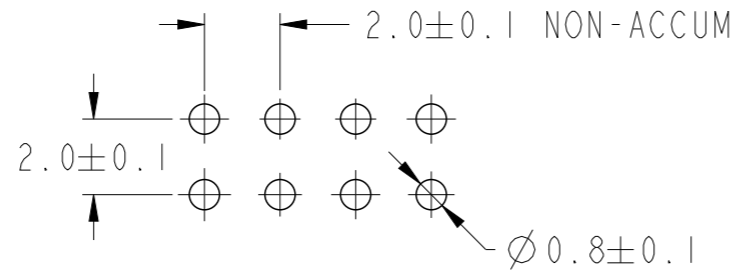


FIG. 1

SEE NOTE 3



RECOMMENDED HOLE LAYOUT
SCALE 5:1

dr	Andrew Yong	2010/10/22	projection	MM	size	A3	scale	9:1	
eng	Yuan-Yuan Bao	2021/08/10			ecn no		ELX-N-41765-1		
chr	-	-			rel level		Released		
appr	Tim Yao	2021/08/11	product family		-		-		
			MINITEK II R/A HEADER			dwg no		94277	
cat. no.			-			Product - Customer Drw		rev	F
sheet 2 of 2									